

ABSTRACT

The present invention provides a top ring or a substrate polishing apparatus capable of achieving a polishing profile further consistent between the central side of a polygonal substrate and the outer edge side of the substrate. A top ring for holding a polygonal substrate is proposed. The top ring includes a base member coupled to a rotational shaft, a substrate suction member, and a biasing mechanism. The substrate suction member includes a substrate suction body having a substrate suction surface for sucking the substrate and provided in communication with a pressure reduction module, a shielding member configured to shield an opposite surface of the substrate suction body from the substrate suction surface, and a frame member connected to the shielding member so as to surround at least a part of the base member. The biasing mechanism has a first end portion in contact with the base member and a second end portion in contact with the frame member, and is configured to apply a biasing force in a direction for moving the base member and the frame member toward or away from each other.

Figure 3